

Fig. 1 (1)

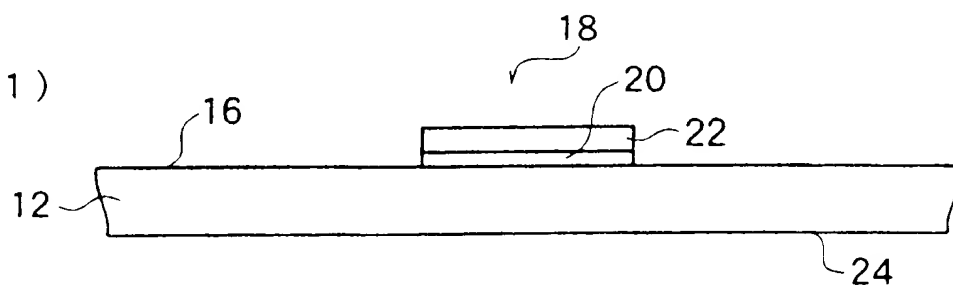


Fig. 1 (2)

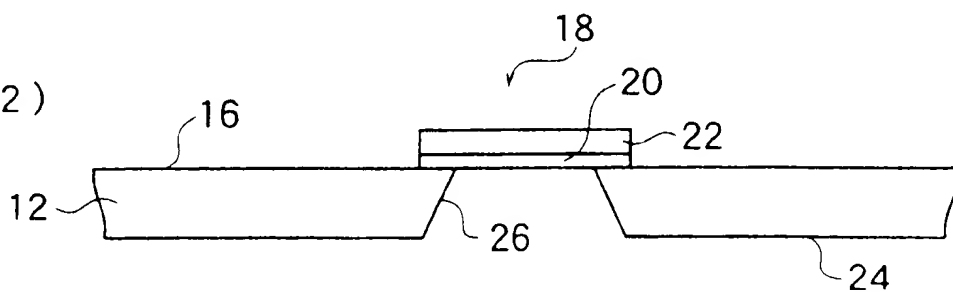


Fig. 1 (3)

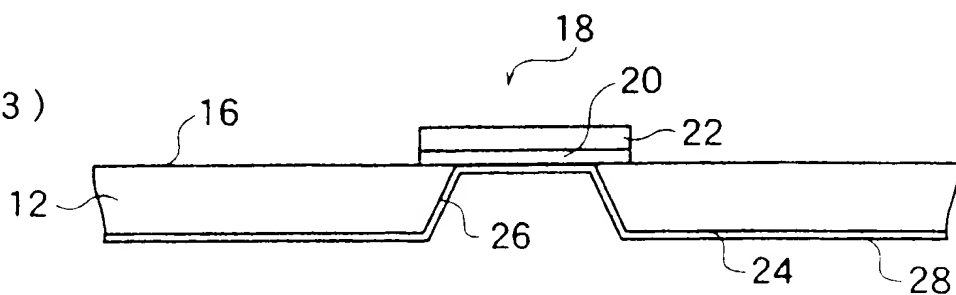


Fig. 1 (4)

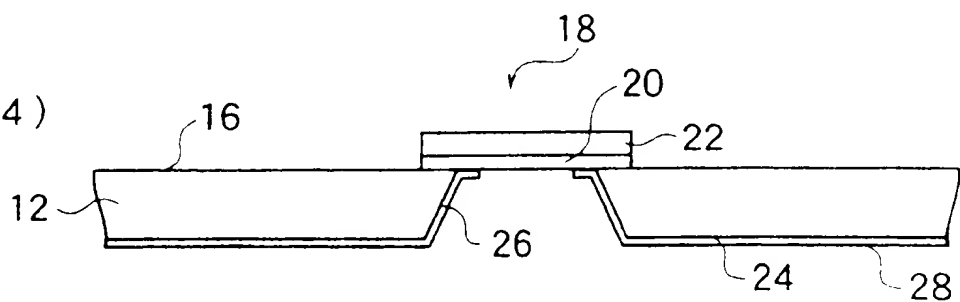


Fig. 2 (1)

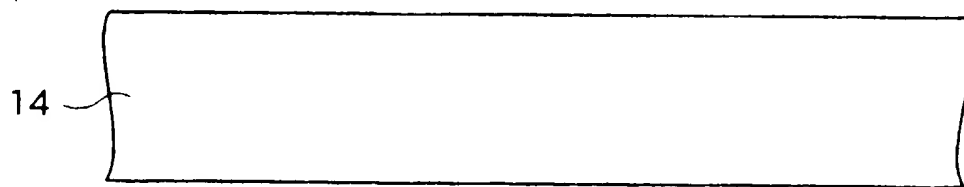


Fig. 2 (2)

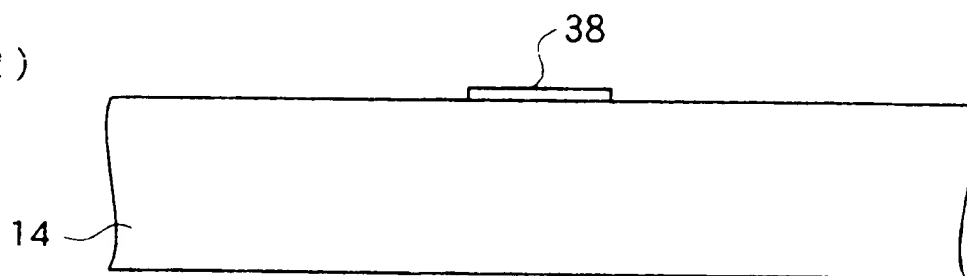


Fig. 2 (3)

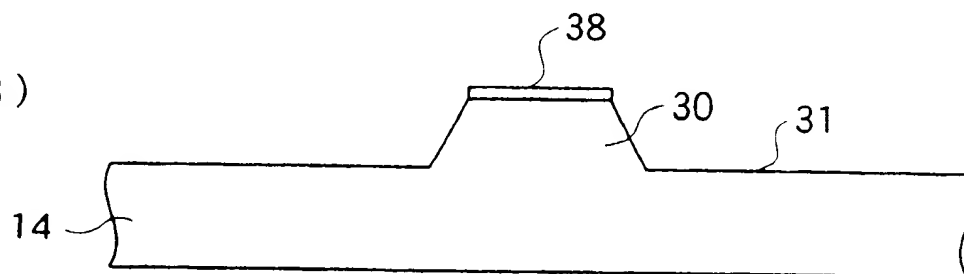


Fig. 2 (4)

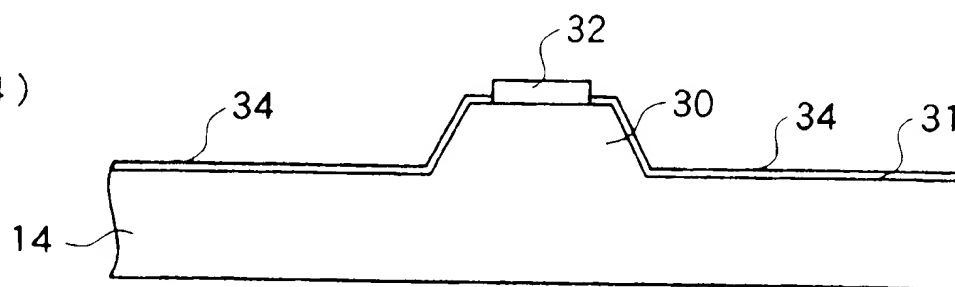


Fig. 3 (1)

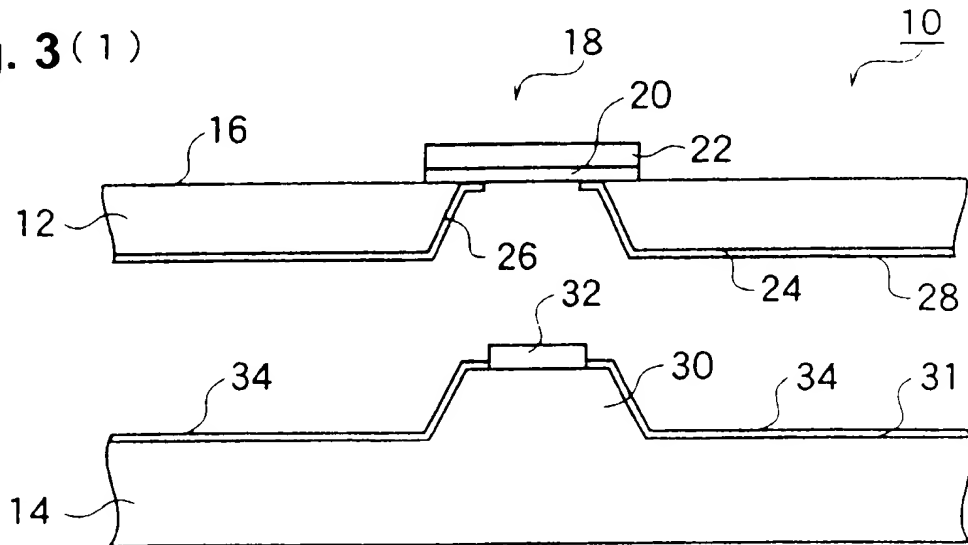
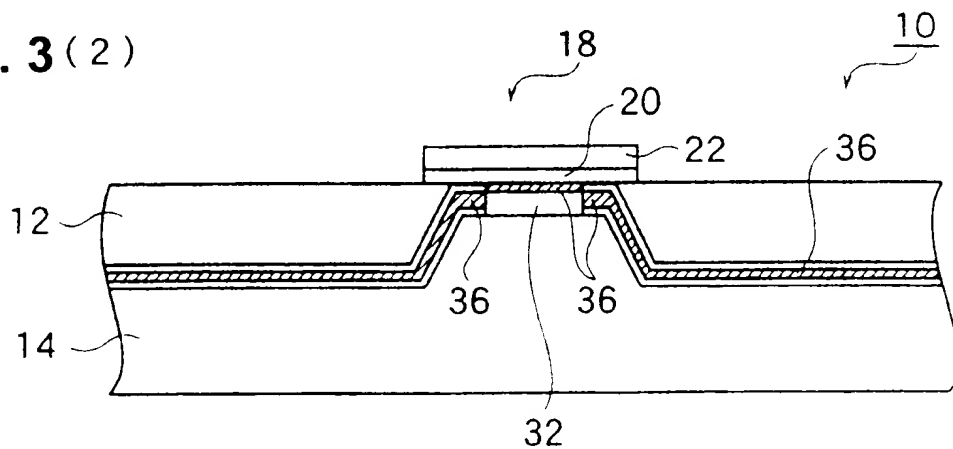


Fig. 3 (2)



- | | |
|--------------------------------|-------------------------|
| 10 : Semiconductor device | 16 : Surface |
| 12 : First semiconductor chip | 18 : Electrode |
| 14 : Second semiconductor chip | 32 : Abutting electrode |

Fig. 4 (1)

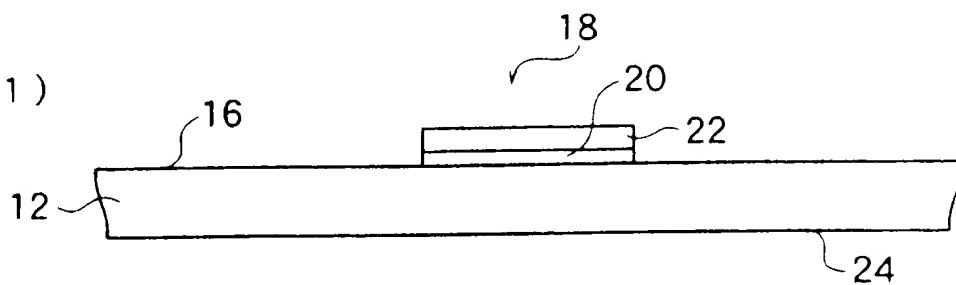


Fig. 4 (2)

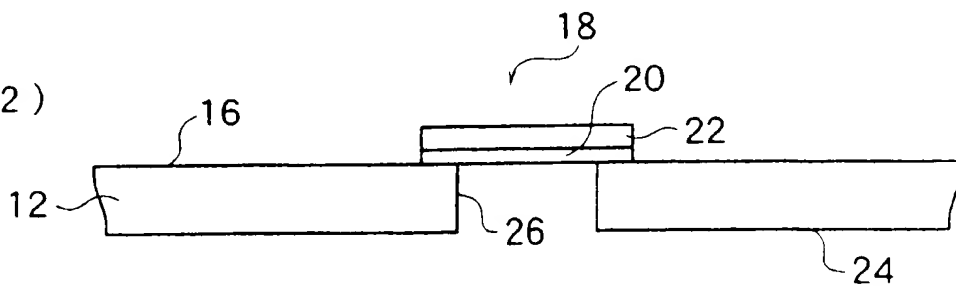


Fig. 4 (3)

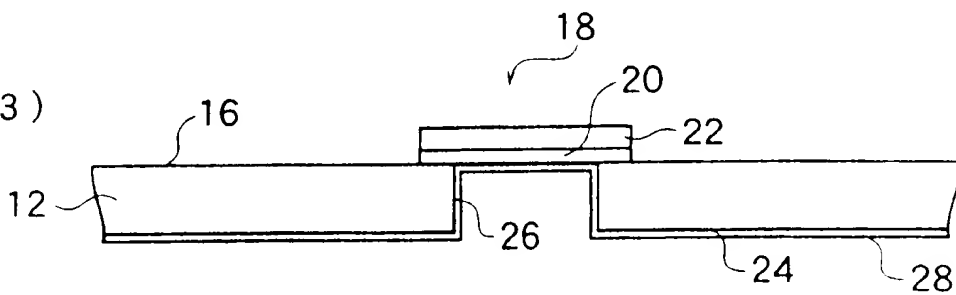


Fig. 4 (4)

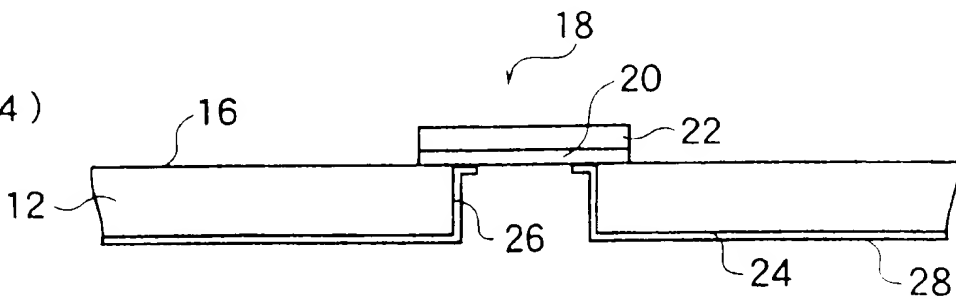


Fig. 5

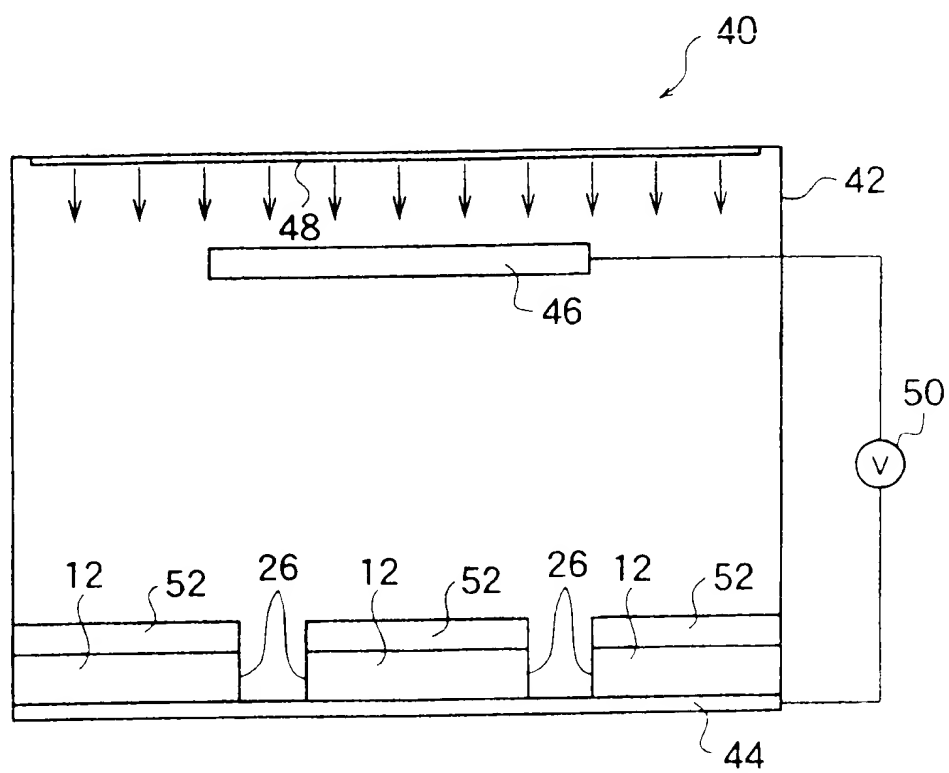


Fig. 6 (1)

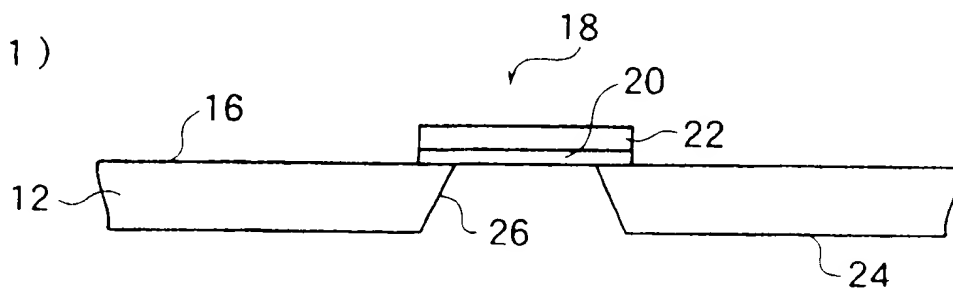


Fig. 6 (2)

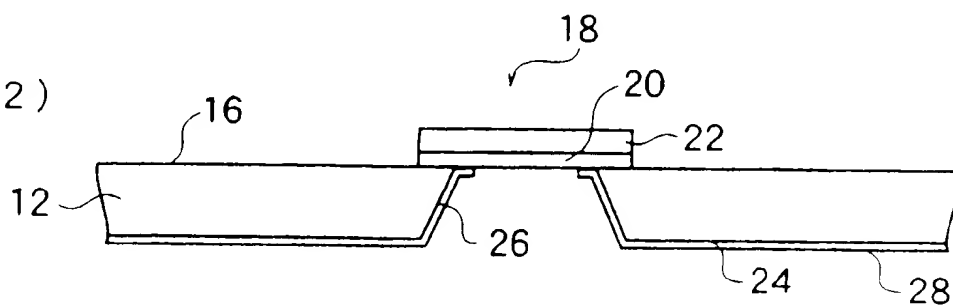


Fig. 6 (3)

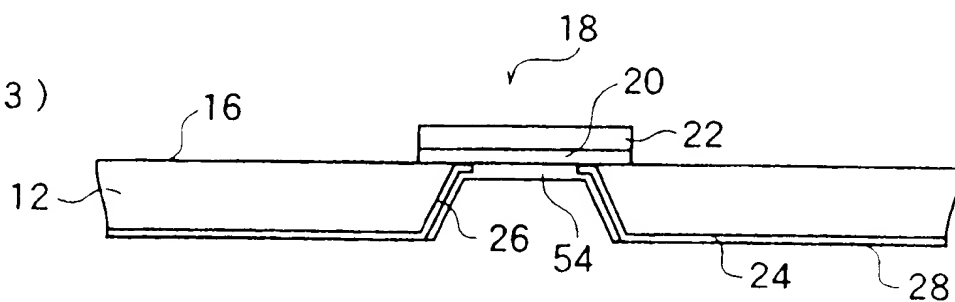


Fig. 6 (4)

